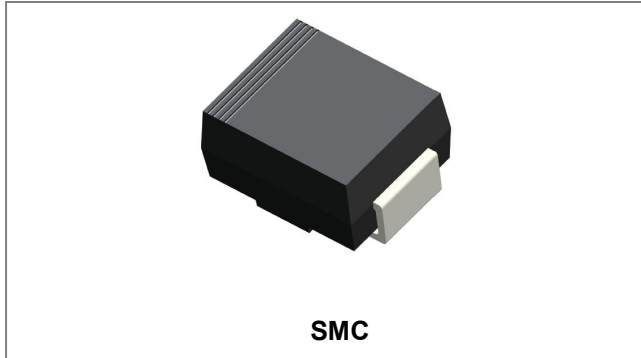


## SK38 SCHOTTKY RECTIFIER



### Features

- Schottky Barrier Chip
- Guard Ring Die Construction for Transient Protection
- High Current Capability
- Low Power Loss, High Efficiency
- High Surge Current Capability
- Terminals finish: 100% Pure Tin
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

### Circuit Diagram



### Mechanical Data

- Case: Low Profile Molded plastic
- Terminals: Plated leads solderable per MIL-STD-750, Method 2026 guaranteed
- Polarity: Color band or cathode Notch
- Mounting Position: Any
- Weight: 0.21grams(approx)

### Maximum Ratings:

Characteristics	Symbol	Condition	Max.	Units
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{RWM}$ $V_R$	-	80	V
Average Rectified Forward Current	$I_{F(AV)}$	50% duty cycle @ $T_L=75^\circ\text{C}$ , rectangular wave form	3	A
Peak One Cycle Non-Repetitive Surge Current	$I_{FSM}$	8.3ms, Half Sine pulse, $T_c = 25^\circ\text{C}$	110	A

### Electrical Characteristics:

Characteristics	Symbol	Condition	Typ.	Max.	Units
Forward Voltage Drop*	$V_{F1}$	@ 3A, Pulse, $T_J = 25^\circ\text{C}$	0.58	0.79	V
	$V_{F2}$	@ 3A, Pulse, $T_J = 125^\circ\text{C}$	0.55	0.74	V
Reverse Current*	$I_{R1}$	@ $V_R = \text{rated } V_R, T_J = 25^\circ\text{C}$	0.02	1.0	mA
	$I_{R2}$	@ $V_R = \text{rated } V_R, T_J = 125^\circ\text{C}$	3	30.0	mA
Junction Capacitance	$C_T$	@ $V_R = 5\text{V}, T_c = 25^\circ\text{C}, f_{SIG} = 1\text{MHz}$	110	250	pF
Series Inductance	$L_S$	Measured lead to lead 5 mm from package body	8.0	-	nH
Voltage Rate of Change	dv/dt	-	-	10,000	V/ $\mu\text{s}$

\* Pulse width < 300  $\mu\text{s}$ , duty cycle < 2%

**Thermal-Mechanical Specifications:**

Characteristics	Symbol	Condition	Specification	Units
Junction Temperature	$T_J$	-	-55 to +150	°C
Storage Temperature	$T_{stg}$	-	-55 to +150	°C
Typical Thermal Resistance Junction to Case	$R_{\theta JA}$	DC operation	55	°C/W
Approximate Weight	wt	-	0.21	g

**Ratings and Characteristics Curves**

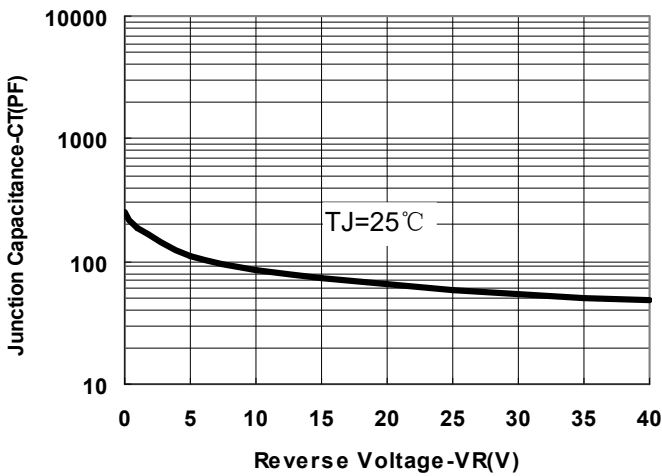


Fig.1-Typical Junction Capacitance

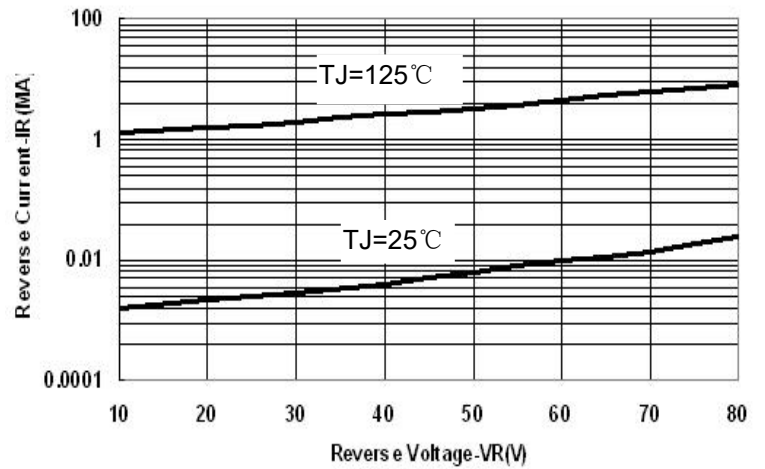


Fig.2-Typical Values Of Reverse Current

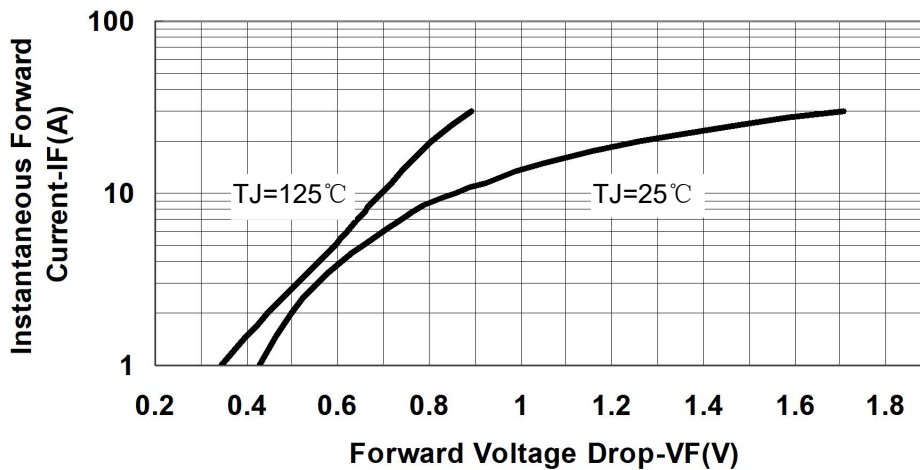
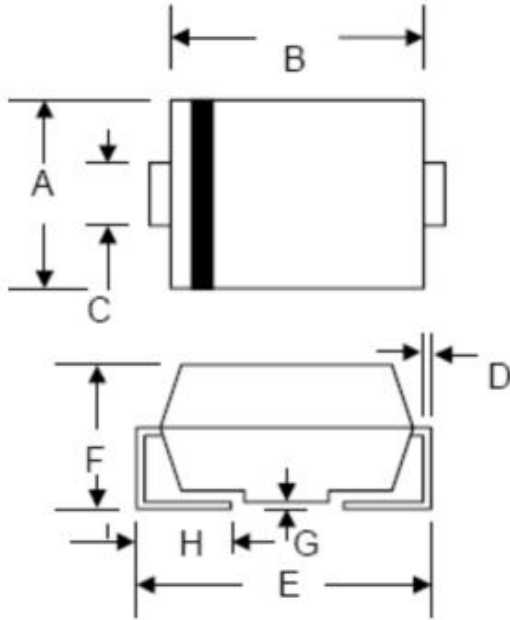


Fig.3-Typical Forward Voltage Drop Characteristics

**Mechanical Dimensions SMC**



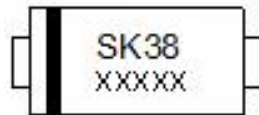
SYMBOL	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	5.59	6.22	0.220	0.245
B	6.60	7.11	0.260	0.280
C	2.75	3.25	0.108	0.128
D	0.152	0.305	0.006	0.012
E	7.75	8.25	0.305	0.325
F	2.00	2.95	0.079	0.116
G	0.051	0.203	0.002	0.008
H	0.76	1.60	0.030	0.063

**Ordering Information**

Device	Package	Shipping
SK38	SMC (Pb-Free)	3000pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

**Marking Diagram**

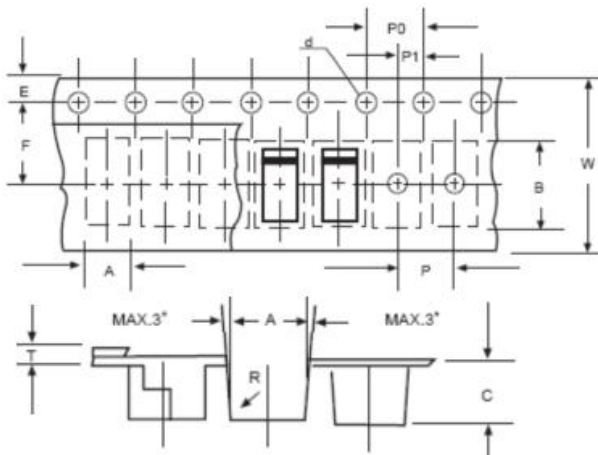


Where XXXXX is YYWWL

- SK = Device Type
- 3 = Forward Current (3A)
- 8 = Reverse Voltage (80V)
- YY = Year
- WW = Week
- L = Lot Number

**Cautions:** Molding resin  
Epoxy resin UL:94V-0

**Carrier Tape Specification SMC**



SYMBOL	Millimeters	
	Min.	Max.
A	5.90	6.10
B	8.20	8.40
C	2.40	2.60
d	1.40	1.60
E	1.40	1.60
F	7.60	7.70
P	7.90	8.10
P0	3.90	4.10
P1	3.90	4.10
T	-	0.600
W	15.80	16.20

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